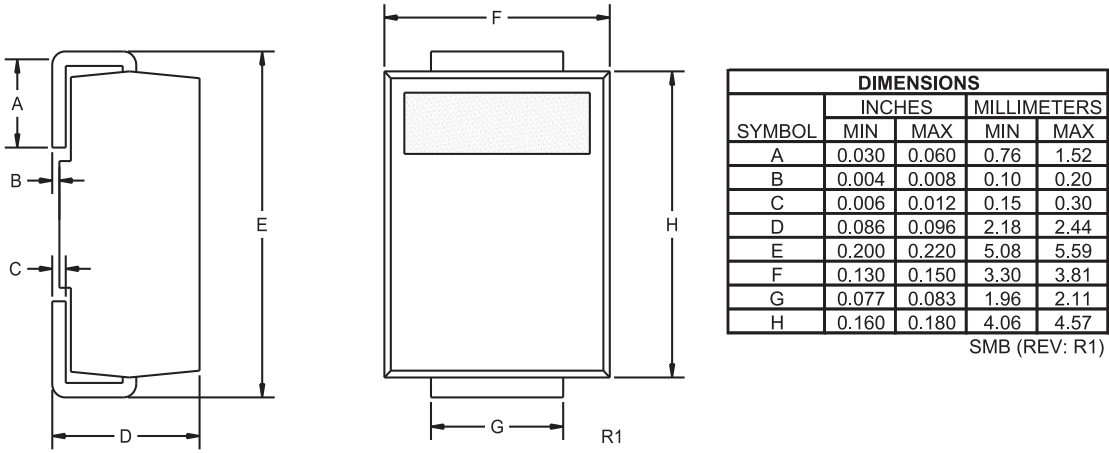


Package Details

SMB Case



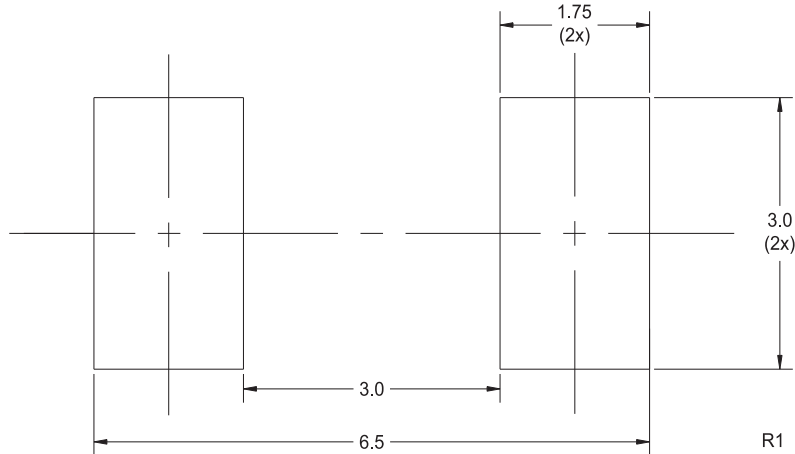
Mechanical Drawing



Lead Code:
Reference individual device datasheet.

Part Marking: 3-6 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



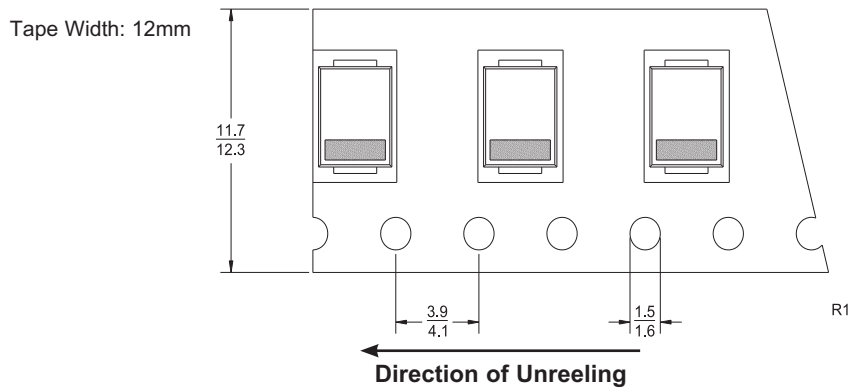
R2 (4-March 2010)

Package Details

SMB Case



Tape Dimensions and Orientation (Dimensions in mm)



* Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

13" Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:

Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
13"	5	15,000	15x4x15	38x10x38	8	4
	14	42,000	15x15x9	38x38x23	21	10
	26	78,000	15x15x18	38x38x46	39	18

Ordering Information

- For devices taped and reeled on 13" reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R2 (4-March 2010)

Material Composition Specification

SMB Case



Device average mass 92 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.83%	0.76	Si	7440-21-3	0.83%	0.76	8,262
leadframe	copper	37%	34.04	Cu	7440-50-8	37%	34.04	370,032
die attach	high temperature solder paste	2.45%	2.25	Pb	7439-92-1	2.26%	2.081	22,622
				Sn	7440-31-5	0.12%	0.113	1,228
				Ag	7440-22-4	0.06%	0.056	609
encapsulation*	EMC	58.96%	54.23	silica	7631-86-9	40.09%	36.88	400,904
				epoxy resin	29690-82-2	11.79%	10.85	117,945
				phenol resin	9003-35-4	5.89%	5.42	58,918
				Sb ₂ O ₃	1309-64-4	0.59%	0.542	5,892
				Br	7726-95-6	0.59%	0.542	5,892
	EMC GREEN	58.96%	54.23	silica (fused)	60676-86-0	45.4%	41.76	453,953
				epoxy resin	29690-82-2	5.9%	5.423	58,951
				phenol resin	9003-35-4	5.72%	5.26	57,179
				carbon black	1333-86-4	0.18%	0.163	1,772
				metal hydroxide	1309-42-8	1.77%	1.628	17,697
plating**	tin/lead process	0.77%	0.71	Sn	7440-31-5	0.62%	0.566	6,153
				Pb	7439-92-1	0.15%	0.142	1,544
	matte tin	0.77%	0.71	Sn	7440-31-5	0.77%	0.708	7,696

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix "LEAD FREE" to part number.

For Tin/Lead plating, add suffix "TIN/LEAD" to part number.

No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R4 (3-June 2011)